



Trion® Package Marking Format Change

Dear Efinix Customer,

Efinix Inc. is providing this notification of change to Trion® T04/08 and T13/T20 package marking format. The proposed change is a “cosmetic” change to the appearance of the packaged parts. No impact to Form, Fit and Function (FFF) is anticipated.

Change Description:

1. T04/T08 FBGA81

Line 2 of package marking has its Circuit Design Revision code omitted from package marking.

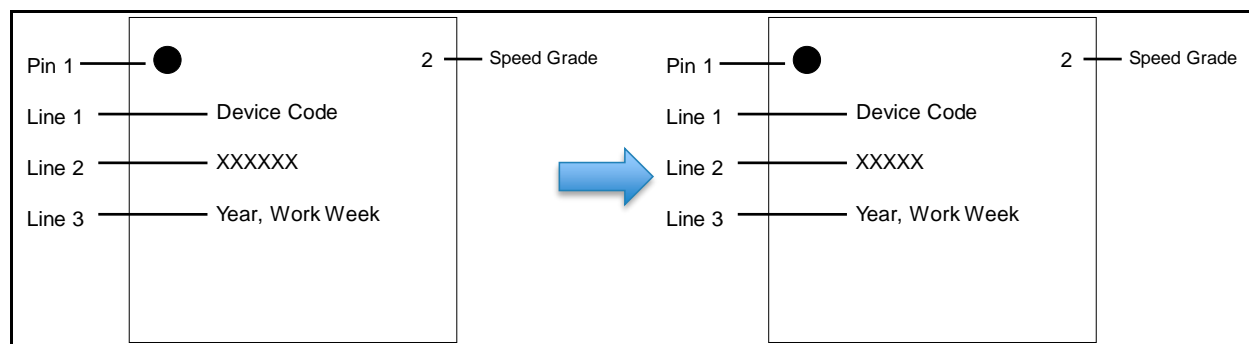


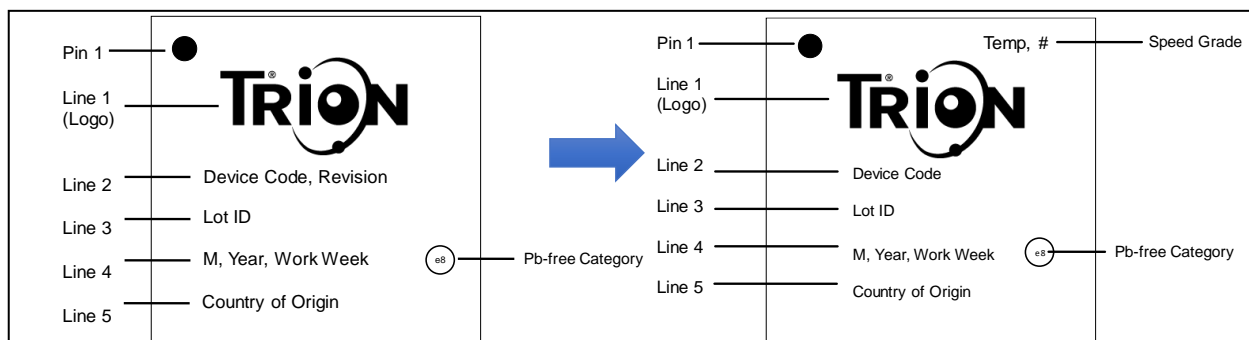
Figure 1: Illustration of current vs. proposed change to the package marking format for FBGA81.

2. T13/T20 FBGA169 & FBGA256

Line 2 of package marking has its Temperature Grade and Circuit Design Revision codes omitted from package marking.

Added Speed Grade marking at top right of package to indicate Temperature Grade + device Bin Speed.

Figure 2: Illustration of current vs. proposed change to the package marking format for FBGA169 and FBGA256.





Product Change Notification (PCN) Number: PCN-1907-001

Issue Date: 12-July-2019

Affected Products:

T04_FBGA81	T08_FBGA81
T13_FBGA169	T13_FBGA256
T20_FBGA169	T20_FBGA256

Affected Manufacturing Facilities:

OSAT A

Reason for Change:

Enhances product traceability and provides clear indication of Trion® T13/T20 Speed Grade information on packaged parts.

Date of Implementation:

Trion® T04/08 and T13/T20 with manufacturing date code 1928 (inclusive) onward.

Upon receipt of PCN: If a written request for additional information or rejection is not provided to Efinix Inc. prior to <11-October-2019>, the PCN will be considered accepted.

Supporting Data:

Not applicable to this PCN.

Contact:

For more information, please contact Sales & Marketing or Quality Assurance Engineering in your region.